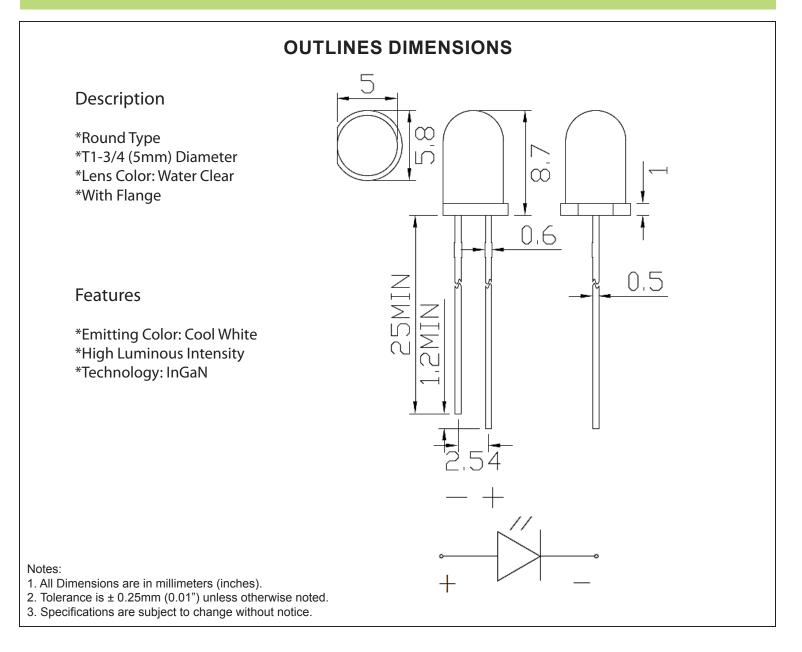


SPECIFICATIONS

CLA50CW2C



| Part Number | Chip Material | Color of Emission | Lens Type | Viewing Angle |
|-------------|---------------|-------------------|-------------|---------------|
| CLA50CW2C | InGaN | White | Water Clear | 15° |



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ABSOLUTE MAXIMUM RATINGS

Parameter Symbol Max Rating Unit 100 **Power Dissipation** PD mW 60 **Pulse Current Forward Current** IFP mA 30 **Continuous Forward Current** IF mΑ V **Reverse Voltage** VR 5 **Operating Temperature Range** TOPR -25~+85 °C Storage Temperature Range °C Tstg -30~+85 IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec

OPTICAL-ELECTRICAL CHARACTERISTICS

Value Parameter Test Condition Unit Symbol Min Тур Max 15000 17500 Luminous Intensity Iv I_F = 20mA _ mcd Forward Voltage I⊧ = 20mA 3.2 3.4 V VF 5 $V_R = 5V$ _ Reverse Leakage Current IR _ μA $2\theta 1/2$ I_F = 20mA 15 _ Viewing Angle _ deg 6000 6500 Correlated Color Temperature CCT _ I_F = 20mA Κ 0.31 Х _ **Chromacticity Coordinates** I_F = 20mA Y 0.32 _ _

*Tolerance of viewing angle: -10 / +5 deg.



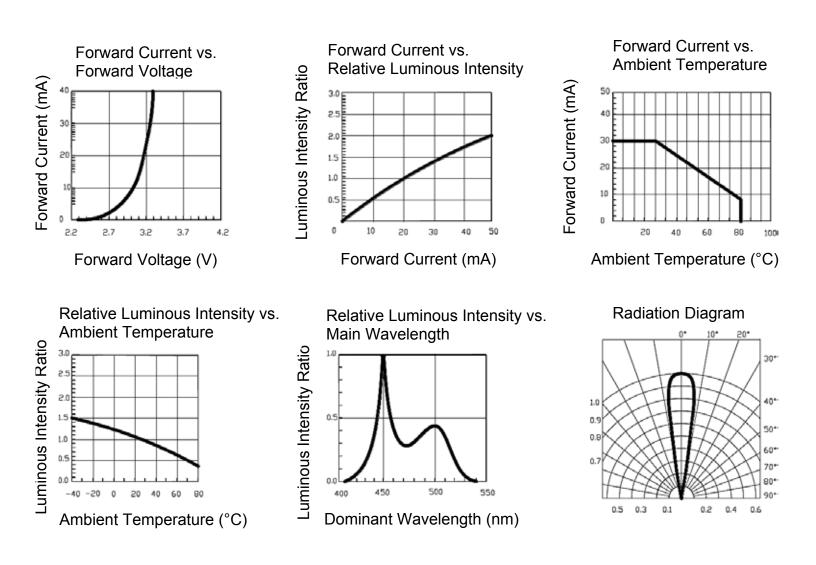
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(TA=25°C)

| (TA=25°C) |
|-----------|
|-----------|



OPTICAL CHARACTERISTIC CURVES





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SOLDERING CONDITIONS – LAMP TYPE LED

* Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.

* Recommended soldering conditions

| Dip Soldering | | | | |
|-------------------------|--|--|--|--|
| Pre-Heat | 100 °C Max | | | |
| Pre-Heat Time | 60 Second Max | | | |
| Solder Bath Temperature | 260 °C Max | | | |
| Dippng Time | 5 Second Max | | | |
| Dipping Position | No lower than 3mm from the base of the epoxy | | | |

| Hand Soldering | | | | |
|--|--|--|--|--|
| | 3mm Series | Others | | |
| Temperature Soldering Time Position | 300 °C Max 3 Second Max No closer than 3mm from the base of the epoxy | 350 °C Max 3 Second Max No closer than 3mm from the base of the epoxy | | |

* Do not apply any stress to the lead. Particularly when heated.

- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.



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